# **Specification of Thermoelectric Module**

TES1-07139

## **Description**

The 71 couples, 23mm x 23mm size module is a single stage module which is made of our high performance ingot to achieve superior cooling performance and 70°C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

### Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

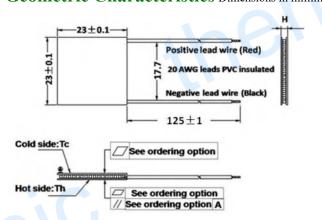
# Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

## **Performance Specification Sheet**

	1	i		
Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>	
DT <sub>max</sub> (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U <sub>max</sub> (Voltage)	9.0	9.4	Voltage applied to the module at DT <sub>max</sub>	
I <sub>max</sub> (Amps)	4.1	4.1	DC current through the modules at DT <sub>max</sub>	
Q <sub>Cmax</sub> (Watts)	23.0	24.8	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (Ohms)	1.67	1.80	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

# Geometric Characteristics Dimensions in millimeters



# **Manufacturing Options**

### A. Solder:

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217°C)

2. SS: Silicone sealant

3. T240: SbSn (Tmelt =  $240^{\circ}$ C)

3. EPS: Epoxy sealant

### C. Ceramics:

### **D. Ceramics Surface Options:**

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)

1. Blank ceramics (not metalized)

2. Aluminum Nitride (AlN)

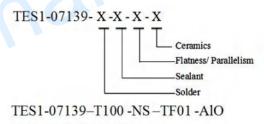
2. Metalized

# **Ordering Option**

Suffix	Thickness	Flatness/	Lead wire length(mm)
	H (mm)	Parallelism (mm)	Standard/Optional length
TF	0:3.2± 0.1	0: 0.07/0.07	125±1/Specify
TF	$1:3.2 \pm 0.03$	1: 0.025/0.025	125±1/Specify

Eg. TF01: Thickness 3.2± 0.1 (mm) and Flatness 0.025/0.025 (mm)

# Naming for the Module



T100: BiSn(Tmelt=138°C)

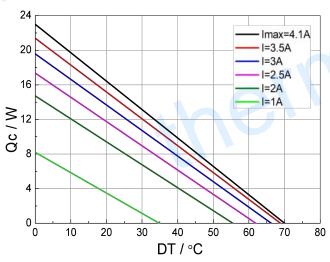
NS: No sealing AlO: Alumina white 96%

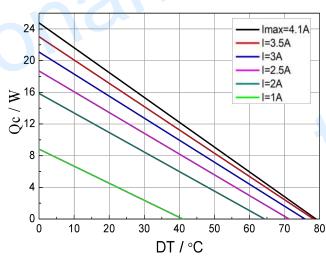
# **Specification of Thermoelectric Module**

**TES1-07139** 

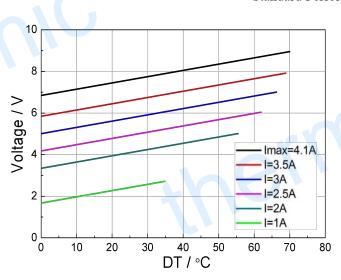
### Performance Curves at Th=27 °C

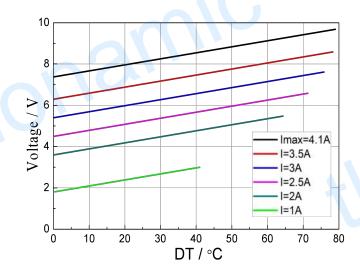
### Performance Curves at Th=50 °C



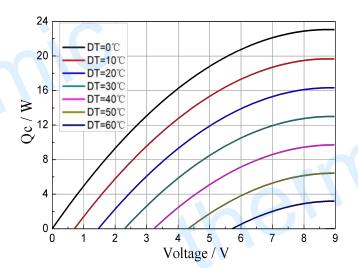


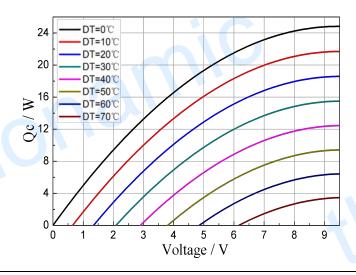
Standard Performance Graph Qc= f(DT)





Standard Performance Graph V= f(DT)





Standard Performance Graph Qc = f(V)

# **Specification of Thermoelectric Module**

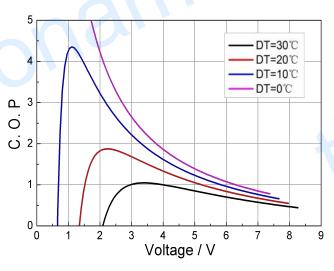
**TES1-07139** 



# 5 4 DT=30°C DT=20°C DT=10°C DT=0°C 1

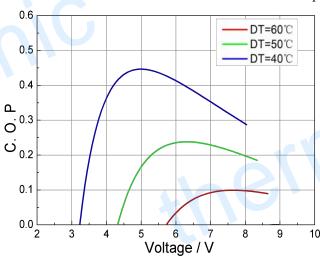
Voltage / V

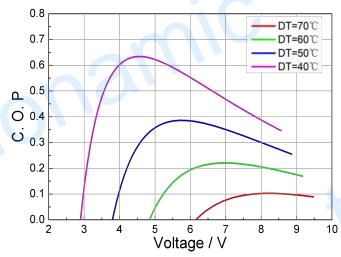
### Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C

8





Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

**Remark:** The coefficient of performance (COP) is the cooling power Qc/Input power ( $V \times I$ ).

# **Operation Caution**

0

2

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC

Note: All specifications subject to change without notice.